

CKC21X683MWGACTU

Aliases (CKC21X683MWGAC7800) KC-LINK Comm COG, Ceramic, 0.068 uF, 20%, 650 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 2220



Click here for the 3D model.

General Information			
Series	KC-LINK Comm COG		
Style	SMD Chip		
Description	SMD, MLCC, FT-CAP, Ultra- Stable		
Features	FT-CAP, Ultra-Stable		
RoHS	Yes		
Termination	Flexible Termination		
Marking	No No		
AEC-Q200			
Typical Component Weight	260 mg		
Shelf Life	78 Weeks		
MSL	1		

0.1% 1 kHz 1.0Vrms

0% Loss/Decade Hour 14.7059 GOhms

		Specifications	
	2220	Capacitance	0.068 uF
	5.9mm +/-0.75mm	Measurement Condition	1 kHz 1.0Vrms
	5mm +/-0.4mm	Tolerance	20%
	2mm +/-0.20mm	Voltage DC	650 VDC
0.7mm +/-0.35mm	0.7mm +/-0.35mm	Dielectric Withstanding Voltage	845 VDC
		Temperature Range	-55/+150°C
		Temp. Coefficient	COG
	T&R, 180mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	500		

Dissipation Factor

Insulation Resistance

Aging Rate

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions Chip Size

Packaging

Packaging Specifications

Packaging Quantity

L W

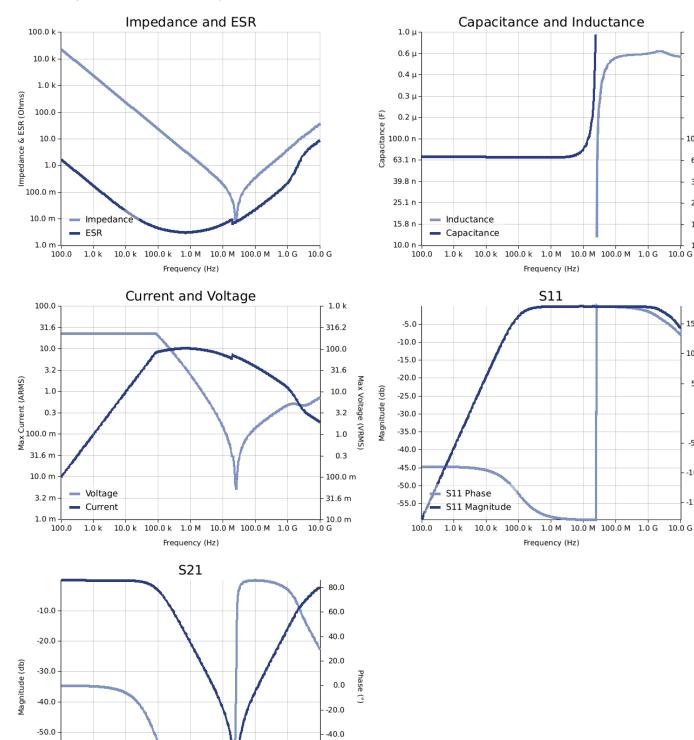
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Simulations

For the complete simulation environment please visit K-SIM.



-60.0

-80.0

-60.0

-70.0

S21 Phase
S21 Magnitude

100.0 1.0 k 10.0 k 100.0 k 1.0 M 10.0 M 100.0 M 1.0 G 10.0 G Frequency (Hz) 1.0 n

0.6 n

0.4 n

0.3 n

100.0 p fance 63.1 p (H)

39.8 p

25.1 p

15.8 p

10.0 p

150.0

100.0

50.0

0.0

-50.0

-100.0

-150.0

Phase (°)

0.2 n a



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.